| Contact Name Title - Contact Product-Env-Stewards Product Enviro Compliance Authorized Representative* Product-Env-Stewards Product Enviro Compliance NA Product-Env-Stewards@onsemi.com Phone - Representative* Phone - Representative* Phone - Representative* Phone - Representative* Product-Env-Stewards@onsemi.com Requester Item Number Mfr Item Number Mfr Item Name Effective Date Version Manufacturing Site Weight* UOM Un | IPC ASSOCIATION CONNECTINE ELECTRONICS INDUSTRIES | Material Composit © Copyright 2005. IPC, international and Pan-An | Bannockbu | urn, Illinois. A | ll rights reserved un | nder both | This docume level parts, th | ent is a declaration | tion of encom | the substances passes all lowe | within the | manufacture terials for wh | er listed it hich the m | em. Note: anufacture | if the item is an as er has engineering | sembly with low responsibility. |
|--|--|---|-------------|---------------------------|-----------------------|---------------------|--------------------------------|-------------------------|------------------|-----------------------------------|----------------|---------------------------------|----------------------------|-------------------------|--|------------------------------------|
| Company name* Company name* Company unique ID Unique ID Authority Description Contact Name Contact Name Title - Contact Title - Contact Product Enviro Compliance NA Product-Env-Stewards | 1752-21.1 | | | | | | k | | | | | | als and Mf | g Informa | tion | |
| Insemi Contact Name Title - Contact Product Enviro Compliance Intel - Representative Product Enviro Compliance Intel - Representative Intel - Compliance Intel - Contact* | Supplier Inform | ation | | | | | | | | | | | | | | |
| Product-Env-Stewards Under Env-Stewards Under Under Under Env-Stewards Under Un | Company name* Company unique ID | | | | | Unique ID Authority | | | | | Response Date* | | | | | |
| Product-Env-Stewards Authorized Representative* Product-Env-Stewards Authorized Representative* Product-Env-Stewards Product Enviro Compliance Product-Env-Stewards Product-Env-S | nsemi | | | | | | | | | | | | 2025-05- | 11 | | |
| Title - Representative Phone - Representative* Email - Representative* Product-Env-Stewards Product Enviro Compliance NA Product-Env-Stewards Product Enviro Compliance NA Product-Env-Stewards@onsemi.com Requester Item Number Mfr Item Number Mfr Item Name Effective Date Version Manufacturing Site Weight* UOM Un NCP161AFCS280T2G CSP LDO 450mA, Active Discharge 2025-05-11 CNQ 0.3449 mg Each Manufacturing Proccess Information Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Side Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles SnAgCu CU Alloy 1 260 C 30 seconds 3 | ontact Name | | | Title - Contact | | | I | Phone - Contact* | | | | Email - Contact* | | | | |
| Product-Env-Stewards Requester Item Number Mfr Item Number Mfr Item Number Mfr Item Name Effective Date Version Manufacturing Site Weight* UOM Un NCP161AFCS280T2G CSP LDO 450mA, Active Discharge 2025-05-11 CNQ 0.3449 mg Each Manufacturing Process Information Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating SnAgCu CU Alloy 1 260 C 30 seconds 3 | Product-Env-Stewa | ards | | Product Enviro Compliance | | | | NA | | | | Product-Env-Stewards@onsemi.com | | | | |
| Requester Item Number | uthorized Represen | ntative* | | Title - Representative | | | I | Phone - Representative* | | | | Email - Representative* | | | | |
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| Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles | Requeste | er Item Number | Mfr Item | Number | Mfr Item Name | | | Effective Date | e Vei | rsion | Manufactu | ring Site | V | Veight* | UOM | Unit Type |
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| SnAgCu CU Alloy 1 260 C 30 seconds 3 omments | | | | omerical Daga | Nlav. I | CTD 020 MCI | Datina | Dook Duo | anna Da | ody Tammanatu | ma May T | ima at Daak | Tommorati | wo Num | har of Doflaw Cw | Jac |
| omments | | | | <u> </u> | | -51D-020 MSL | Kating | | <u> </u> | | ime at Peak | | | ber of Kellow Cyc | cies | |
| | | | C | U Alloy | 1 | | | 200 | | IC IC | 30 | | second | 18 3 | | |
| VCI 1 " MAXIMUM UMC AC PEAK COMPETATOR OUT MY SOLUCIMY IS TO SECONDS | | ima at naak tampareture d | luring cold | doring is 10 20 | 0 seconds | | | | | | | | | | | |
| or more information regarding material composition please refer to page 3 | | | | | | | | | | | | | | | | |

| RoHS Material Composition Declaration | | | Declaration Type * | Detail | ed |
|--|---|---|---|---|---|
| Directive 2015/863/EU amending RoHS Directive 2011/65/EU | | ium (Cr6+), Polybrominated Biphenyls (PB) | erial for Cadmium and quantity limit of 0.1% b B), Polybrominated Diphenyl Ethers (PBDE), a | | |
| cadmium, hexavalentchromium, polybromin contains a RoHS restricted substance inexce encompass all such components. Supplier cet as of the date that Supplier completes this Company acknowledges that Supplier may hindependently verified information provided certification in this paragraph. If the Compan | nated biphenyls and/or polybrominated diphess of an applicable quantity limit, please indriffes that it gathered the information it provom. Supplier acknowledges that Company wave relied on informationprovided by others of the supplier agrees that, at a minimusy and the Supplier enter into a written agree yesource of the Supplier's liability and the C | enyl ethers (each a "RoHS restricted substan licate below which, if any, RoHS exemption vides in this form using appropriate methods vill rely on this certification in determining the s in completing this form, and that Supplier um, itssuppliers have provided certifications ement with respect to the identified part, the tompany's remedies for issues that arise rega | s of the European Union member states) of the ce") in excess of the applicable quantity limit is you believe may apply. If the part is an assemb to ensure its accuracy and that such informatio e compliance of its products with European Ur may not have independently verified such infor regarding their contributions to the part, and the erms and conditions of that agreement, including information the Supplier provides in this | dentified above. If a ally with lower level in is true and correct at it in member state la mation. However, in ose certifications are ag any warranty righ | homogeneous material within the part components, the declaration shall to the best of its knowledge and belief, was that implement the RoHS Directive. In situations where Supplier has not the at least as comprehensive as the lats and/or remedies provided as part of |
| RoHS Declaration * 1 - Item | (s) does not contain RoHS restricted substar | nces per the definition above | Supplier A | cceptance * | Accepted |
| Exemption: If the declared item does not applicable exemptions. | contain RoHS restricted substances per t | he definition above except for defined Rol | IS exemptions, then select the corresponding | response in the R | oHS Declaration above and choose all |
| Exemption List Version | EL-2011/534/EU | | | | |
| Declaration Signature | | | | | |
| | | | | | |
| | | e "Accepted" on the Supplier Acceptance | drop-down. This will display the signature a | rea. Digitally sign t | the declaration (if required by the |

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

| Homogeneous Material | Weight | Unit of Measure | Level | Substance | CAS | Exempt | Weight | Unit of Measure |
|-----------------------------|--------|-----------------|----------|---------------|------------------|--------|--------|-----------------|
| Die | 0.2386 | mg | Supplier | Silicon (Si) | 7440-21-3 | | 0.2386 | mg |
| Protection coat | 0.0085 | mg | | Polyimide | proprietary data | | 0.0085 | mg |
| RDL | 0.0076 | mg | Supplier | Titanium (Ti) | 7440-32-6 | | 0.0001 | mg |
| | | | Supplier | Copper (Cu) | 7440-50-8 | | 0.0075 | mg |
| Solder Ball | 0.0902 | mg | Supplier | Silver (Ag) | 7440-22-4 | | 0.0023 | mg |
| | | | Supplier | Tin (Sn) | 7440-31-5 | | 0.0873 | mg |
| | | | Supplier | Copper (Cu) | 7440-50-8 | | 0.0005 | mg |